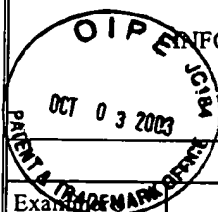


Form PTO-1449



**INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION**  
(use several sheets if necessary)

Docket No.  
P03,0217Serial No.  
10/606,069Applicant  
Gabric et alFiling Date  
June 25, 2003Group Art Unit  
2812-2818**U.S. PATENT DOCUMENTS**

Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date If appropriate
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	AH						
	AI						

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							Yes	No
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<i>DL</i>	AL	101 09 778	09/19/2002	Germany				X
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	AO							

**OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

<i>DL</i>	AP	United States Patent Application Publication no. US 2001/0002732 of Schwarzl et al, published June 7, 2001
	AQ	M.T. Bohr, "Interconnect Scaling - The Real Limiter to High Performance ULSI", <u>IEDM 95</u> , pages 241 - 244
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	AS	T.H. Ning, "0.1 $\mu$ m Technology and BEOL", <u>Mat. Res. Soc. Symp. Proc.</u> , Vol. 427, 1996, pages 17 - 21
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Examiner

*[Signature]*

Date Considered

*7/10/04*

**\*EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.